

Excellent Integrated System Limited

Stocking Distributor

Click to view price, real time Inventory, Delivery & Lifecycle Information:

STMicroelectronics STTH6003CW

For any questions, you can email us directly: sales@integrated-circuit.com

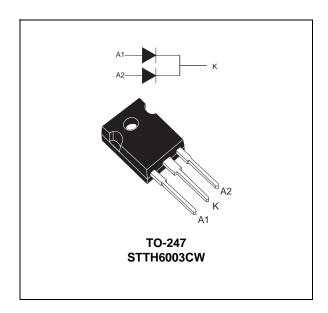




STTH6003

High frequency secondary rectifier

Datasheet - production data



Description

Dual rectifier suited for switch mode power supply and high frequency DC to DC converters. Packaged in TO-247, this device is intended for use in low voltage, high frequency inverters, free wheeling operation, welding equipment and telecom power supplies

Table 1. Device summary

Symbol	Value
I _{F(AV)}	2 x 30 A
V_{RRM}	300 V
V _F (max)	1 V
t _{rr} (max)	55 ns

Features

- Combines highest recovery and voltage performance
- Ultrafast, soft and noise-free recovery
- Low inductance and low capacitance allow simplified layout



Characteristics STTH6003

1 Characteristics

Table 2. Absolute ratings (limiting values, per diode)

Symbol	Parameter	Value	Unit		
V_{RRM}	Repetitive peak reverse voltage			300	V
I _{F(RMS)}	Forward rms current	60	Α		
I _{F(AV)}	Average forward current, $\delta = 0.5$	$T_c = 135^{\circ} \text{ C}$ Per diode $\delta = 0.5$ Per device		30 60	А
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms Si	300	Α	
I _{RSM}	Non repetitive peak reverse current $t_p = 100 \mu s square$			4	Α
T _{stg}	Storage temperature range			-65 to + 175	°C
Tj	Maximum operating junction temperature			175	°C

Table 3. Thermal parameter

Symbol	Parameter	Maximum	Unit
R _{th(j-c)}	Junction to case Per diode Total	1 0.55	°C/W
R _{th(j-c)}	Coupling	0.1	

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_{j \text{ (diode1)}} = P_{\text{(diode1)}} x R_{\text{th(j-c) (per diode)}} + P_{\text{(diode2)}} x R_{\text{th(c)}}$$





STTH6003 Characteristics

Table 4. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Тур	Max.	Unit		
I _R ⁽¹⁾	Deverse leekage eurrant	V 200V	T _j = 25° C	-	-	60			
IR` ′	Neverse leanage current	Reverse leakage current $V_R = 300V$	V _R = 300V	$V_R = 300V$	T _j = 125° C	-	60	600	μΑ
V _E ⁽²⁾	Forward voltage drop	I _F = 30 A	T _j = 25° C	-	-	1.25	V		
VF.	To ward voltage drop		T _j = 125° C	-	0.85	1	V		

- 1. Pulse test: t_p = 5 ms, δ < 2 %
- 2. Pulse test: t_p = 380 μ s, δ < 2 %

To evaluate the maximum conduction losses use the following equation:

$$P = 0.75 \text{ x } I_{F(AV)} + 0.008 I_{F}^{2}_{(RMS)}$$

Table 5. Recovery characteristics

Symbol	Test conditions		Min.	Тур.	Max.	Unit
+	I _F = 0.5 A, I _{rr} = 0.25 A, I _R = 1 A	- T _i = 25° C	-	-	40	ne
t _{rr}	$I_F = 1 \text{ A, } dI_F/dt = -50 \text{ A/}\mu\text{s, } V_R = 30 \text{ V}$	$r_j = 25 \text{ C}$	-	-	55	ns
t _{fr}	$I_F = 30 \text{ A}, dI_F/dt = 200 \text{ A/}\mu\text{s V}_{FR} = 1.1 \text{ x V}_{Fmax}.$ $T_i = 25^{\circ} \text{ C}$	T _i = 25° C	-	-	350	ns
V_{FP}	1 F = 30 Λ, α F/α = 200 Λ/μ3 V FR = 1.1 λ V Fmax.	1, - 25 0	-	-	5	V
S _{factor}	$V_{CC} = 200 \text{ V}, I_{F} = 30\text{A}, dI_{F}/dt = 200 \text{ A/}\mu\text{s}$	T _i = 125° C	-	0.3	-	-
I _{RM}	VCC - 200 V, IF - 30Λ, αΙΕ/αι = 200 Α/μδ	1j = 125 C	-	-	11	Α



Characteristics STTH6003

Figure 1. Conduction losses versus average current (per diode).

Current (maximum values, per diode)

IFM(A)

Tj=125°C
Typical values
Tj=125°C
Maximum values

VFM(V)

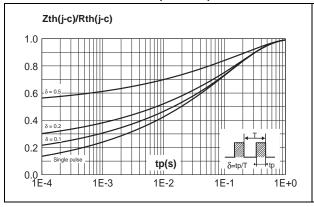
Figure 2. Forward voltage drop versus forward

P1(W) 40 35 30 25 20 15 10 5 **IF(av) (A)** 0 10 15 20 25 30 35

Figure 3. Relative variation of thermal impedance junction to case versus pulse duration (TO-247).

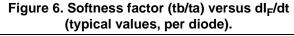
Figure 4. Peak reverse recovery current versus dl_F/dt (90% confidence, per diode).

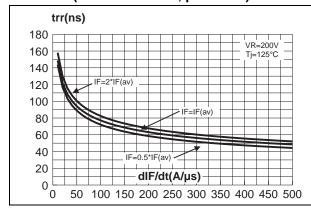
0.2 0.4 0.6 0.8 1.0 1.2 1.4 1.6 1.8 2.0 2.2 2.4 2.6

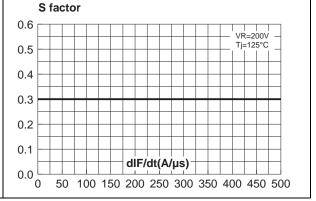


IRM(A) 22 VR=200V 20 Tj=125°C 18 16 14 12 10 8 6 4 2 dIF/dt(A/µs) 0 100 150 200 250 300 350 400 450 500

Figure 5. Reverse recovery time versus dl_F/dt (90% confidence, per diode).







4/9 DocID6144 Rev 6



STTH6003 Characteristics

Figure 7. Relative variation of dynamic parameters versus junction temperature (reference: $T_i = 125$ °C).

Figure 8. Transient peak forward voltage versus dI_F/dt (90% confidence, per diode).

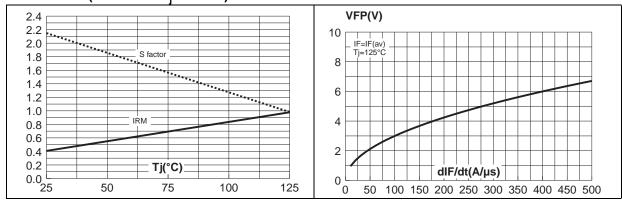
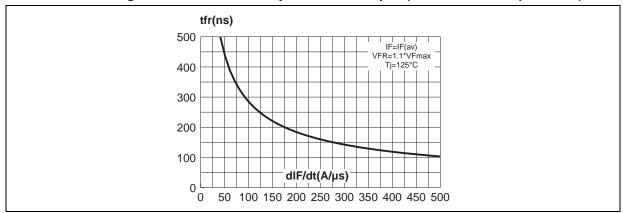


Figure 9. Forward recovery time versus dl_F/dt (90% confidence, per diode).





Package information STTH6003

2 Package information

• Epoxy meets UL 94,V0

Cooling method: by conduction (C)
 Recommended torque values: 0.55 N·m

Maximum torque value: 1.0 N⋅m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK[®] packages, depending on their level of environmental compliance. ECOPACK[®] specifications, grade definitions and product status are available at: www.st.com. ECOPACK[®] is an ST trademark.

Figure 10. TO-247 drawing

HEAT-SINK PLANE

L2

L1

L2

BACK VIEW 0075325, G





STTH6003 Package information

Table 6. TO-247 mechanical data

Dim.	mm.			
Dim.	Min.	Тур.	Max.	
А	4.85		5.15	
A1	2.20		2.60	
b	1.0		1.40	
b1	2.0		2.40	
b2	3.0		3.40	
С	0.40		0.80	
D	19.85		20.15	
E	15.45		15.75	
е	5.30	5.45	5.60	
L	14.20		14.80	
L1	3.70		4.30	
L2		18.50		
ØP	3.55		3.65	
ØR	4.50		5.50	
S	5.30	5.50	5.70	





Ordering information

STTH6003

3 Ordering information

Table 7. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
STTH6006CW	STTH6006CW	TO-247	4.36g	30	Tube

4 Revision history

Table 8. Document revision history

Date	Revision	Changes	
Oct-1999	5C	Previous revision.	
18-Jun-2014	6	Removed ISOTOP package. Updated Section 2: Package information.	





Distributor of STMicroelectronics: Excellent Integrated System Limited

Datasheet of STTH6003CW - DIODE ARRAY GP 300V 30A TO247-3

Contact us: sales@integrated-circuit.com Website: www.integrated-circuit.com

STTH6003

Please Read Carefully:

Information in this document is provided solely in connection with ST products. STMicroelectronics NV and its subsidiaries ("ST") reserve the right to make changes, corrections, modifications or improvements, to this document, and the products and services described herein at any time, without notice.

All ST products are sold pursuant to ST's terms and conditions of sale.

Purchasers are solely responsible for the choice, selection and use of the ST products and services described herein, and ST assumes no liability whatsoever relating to the choice, selection or use of the ST products and services described herein.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted under this document. If any part of this document refers to any third party products or services it shall not be deemed a license grant by ST for the use of such third party products or services, or any intellectual property contained therein or considered as a warranty covering the use in any manner whatsoever of such third party products or services or any intellectual property contained therein.

UNLESS OTHERWISE SET FORTH IN ST'S TERMS AND CONDITIONS OF SALE ST DISCLAIMS ANY EXPRESS OR IMPLIED WARRANTY WITH RESPECT TO THE USE AND/OR SALE OF ST PRODUCTS INCLUDING WITHOUT LIMITATION IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE (AND THEIR EQUIVALENTS UNDER THE LAWS OF ANY JURISDICTION), OR INFRINGEMENT OF ANY PATENT, COPYRIGHT OR OTHER INTELLECTUAL PROPERTY RIGHT.

ST PRODUCTS ARE NOT DESIGNED OR AUTHORIZED FOR USE IN: (A) SAFETY CRITICAL APPLICATIONS SUCH AS LIFE SUPPORTING, ACTIVE IMPLANTED DEVICES OR SYSTEMS WITH PRODUCT FUNCTIONAL SAFETY REQUIREMENTS; (B) AERONAUTIC APPLICATIONS; (C) AUTOMOTIVE APPLICATIONS OR ENVIRONMENTS, AND/OR (D) AEROSPACE APPLICATIONS OR ENVIRONMENTS. WHERE ST PRODUCTS ARE NOT DESIGNED FOR SUCH USE, THE PURCHASER SHALL USE PRODUCTS AT PURCHASER'S SOLE RISK, EVEN IF ST HAS BEEN INFORMED IN WRITING OF SUCH USAGE, UNLESS A PRODUCT IS EXPRESSLY DESIGNATED BY ST AS BEING INTENDED FOR "AUTOMOTIVE, AUTOMOTIVE SAFETY OR MEDICAL" INDUSTRY DOMAINS ACCORDING TO ST PRODUCT DESIGN SPECIFICATIONS. PRODUCTS FORMALLY ESCC, QML OR JAN QUALIFIED ARE DEEMED SUITABLE FOR USE IN AEROSPACE BY THE CORRESPONDING GOVERNMENTAL AGENCY.

Resale of ST products with provisions different from the statements and/or technical features set forth in this document shall immediately void any warranty granted by ST for the ST product or service described herein and shall not create or extend in any manner whatsoever, any liability of ST.

ST and the ST logo are trademarks or registered trademarks of ST in various countries.

Information in this document supersedes and replaces all information previously supplied.

The ST logo is a registered trademark of STMicroelectronics. All other names are the property of their respective owners.

© 2014 STMicroelectronics - All rights reserved

STMicroelectronics group of companies

Australia - Belgium - Brazil - Canada - China - Czech Republic - Finland - France - Germany - Hong Kong - India - Israel - Italy - Japan - Malaysia - Malta - Morocco - Philippines - Singapore - Spain - Sweden - Switzerland - United Kingdom - United States of America

www.st.com



DocID6144 Rev 6 9/9